

# ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	COMPRESSIBLE FILMS SURROUNDING SOLDER CONNECTORS
Application Number :	
Confirmation Number:	
First Named Applicant:	William Bernier
Attorney Docket Number:	FIS920040098US1
Art Unit:	
Examiner:	
Search string:	( 6483191 or 5274913 or 6281452 or 6573122 or 6100114 or 20030230792 ).pn

## US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
DF	1	6483191	2002-11-19	Umezaki			
DF	2	5274913	1994-01-04	Grebe et al			
DF	3	6281452	2001-08-28	Prasad et al			
DI	4	6573122	2003-06-03	Standing			
PF	5	6100114	2000-08-08	Milkovich et al			

## US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
PF	1	20030230792	2003-12-18	Wu et al			

## Signature

Examiner Name	Date
	2122106

**EXAMINER:** Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.